



CALL FOR PAPERS
From Nano to Macro
Power Electronics and Packaging
European Workshop
November the 8th, 2018 - TOURS, FRANCE



Following the success of the *Power Electronics Workshop* organized over the past 9 years in partnership with GREMAN (UMR 7347) and Polytech-Tours, sponsored by ST-Microelectronics and éolane, IMAPS-France proudly announces the 10th edition of the *Power Electronics and Packaging Technical Workshop* to be held in Tours, France on **November the 8th, 2018**. The city of Tours is located along the scenic Loire Valley which is famous for its castles built along the river. For the sixth time, the event's scope becomes international and the workshop will be held in English. **Please, don't miss the date!!**

TECHNICAL COMMITTEE:

Stéphane BELLENGER	EOLANE Angers	France	General Chairman
Daniel ALQUIER	GREMAN Laboratory	France	Co-chairman
Christophe SERRE	ST Microelectronics-Tours	France	Co-chairman
Lars BOETTCHER	FRAUNHOFER Institute	Germany	
Cyril BUTTAY	AMPERE Laboratory	France	
Guillaume CALLERANT	SONCEBOZ	Switzerland	
Jean-Luc DIOT	NOVAPACK	France	
Marc DUCHOSSOY	THALES GROUP	France	
Sébastien JACQUES	GREMAN Laboratory	France	
Guo-Quan LU	VIRGINIA TECH	USA	
Jürgen SCHUDERER	ABB Corporate Research	Switzerland	

We invite speakers to submit abstracts relating to the following topics:

- Power management for transportation and industrial systems
- Energy harvesting systems, from nano to macro (smart grid, wind energy, photovoltaic, etc...)
- Energy conversion systems– from power to emission (lighting, ultrasonic, infrared, etc...)

These topics could be developed around several themes, such as:

- New materials and substrates dedicated to power electronics
- Thermal or thermo mechanical or regulatory constraints (RoHS regulation, REACH, etc...)
- Dedicated technologies for integration and optimisation of power systems, including passive components (weight and size reduction, yield improvement, efficiency, etc...)
- Innovative technologies, materials and processes dedicated to interconnection and packaging (die attach, bonding wire & ribbon wires, 3D power components, etc...)
- Reliability and failure modes (impacts linked to technologies, thermal constraints, radiation, etc...), predictive methods, design of experiments, reliability
- High current and high voltage or extremely high voltage: impact on packaging technologies

Presentations will be 25 minutes in length, including 5 minutes for questions and answers. The abstract submission deadline is June the 30th. Please submit abstracts in English (Conference official language) and word format, including the names of the company or institution, the speaker and associated author(s), the title of the conference and an abstract of 250-600 words. Paper acceptance will be communicated prior to July the 15th.

Following the first workshop day, IMAPS will organize in the evening a specific event followed by a diner.

For further information, please contact Florence VIRETON Tel: +33 (0) 1 39 67 17 73

E-mail: imaps.france@imapsfrance.org; Web: <http://france.imapseurope.org/>

